



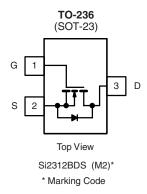
# N-Channel 20 V (D-S) MOSFET

PRODU	PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
	0.031 at V <sub>GS</sub> = 4.5 V	5.0				
20	0.037 at V <sub>GS</sub> = 2.5 V	4.6	7.5			
	0.047 at V <sub>GS</sub> = 1.8 V	4.1				

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC





Ordering Information: Si2312BDS-T1-E3 (Lead (Pb)-free)

Si2312BDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS T	A = 25 °C, unle	ss otherwise r	noted		
Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V <sub>DS</sub>	20		V
Gate-Source Voltage		V <sub>GS</sub>	± 8		
Continuous Drain Current (T, I = 150 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C		5.0	3.9	
Continuous Diam Current (1 <sub>J</sub> = 150 °C)	T <sub>A</sub> = 70 °C	l <sub>D</sub>	4.0	3.1	Α
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	15		A
Avalanche Current <sup>b</sup>	L = 0.1 mH	I <sub>AS</sub>	13		
Single Avalanche Energy	L=0.1 mn	E <sub>AS</sub>	8.45		mJ
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	1.0	0.63	Α
Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	- P <sub>D</sub>	1.25	0.75	W
Fower Dissipation	T <sub>A</sub> = 70 °C		0.80	0.48	VV
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 5 s	В	80	100	
waximum Junction-to-Ambient	Steady State	$R_{thJA}$	120	166	°C/W
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	50	60	

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.

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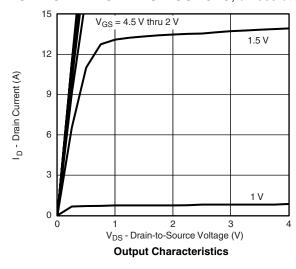
SPECIFICATIONS T <sub>A</sub> = 25 °	C, unless	otherwise noted					
				Limits			
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.45		0.85	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA	
Zoro Cata Valtaga Drain Current		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 ^{\circ}\text{C}$			75	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 4.5 \text{ V}$	15			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 5.0 \text{ A}$		0.025	0.031		
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 4.6 A		0.030	0.037	Ω	
	, ,	V <sub>GS</sub> = 1.8 V, I <sub>D</sub> = 4.1 A		0.036	0.047		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 5.0 A		30		S	
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> = 1.0 A, V <sub>GS</sub> = 0 V		0.8	1.2	V	
Dynamic <sup>b</sup>							
Total Gate Charge	$Q_g$			7.5	12		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 5.0 \text{ A}$		1.4		nC	
Gate-Drain Charge	$Q_{gd}$			1.2			
Gate Resistance	$R_{g}$	f = 1.0 MHz	1.1	2.2	3.3	Ω	
Switching							
Turn-On Delay Time	t <sub>d(on)</sub>			9	15		
Rise Time	t <sub>r</sub>	$V_{DD} = 10 \text{ V}, R_{I} = 10 \Omega$		30	45		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 1.0 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 6 \Omega$		35	55	ns	
Fall Time	t <sub>f</sub>			10	15		
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	1 100 11/14 100 0/		13	25		
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	$I_F = 1.0 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$		4.5	7	nC	

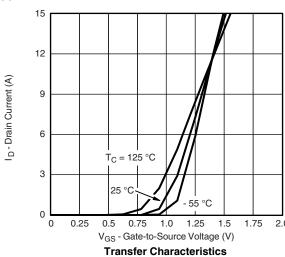
#### Notes

- a. Pulse test: Pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



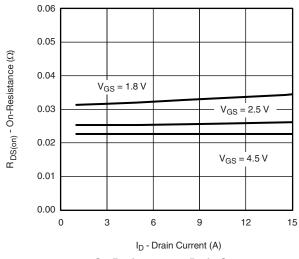




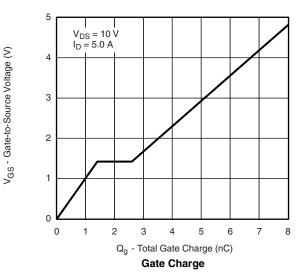


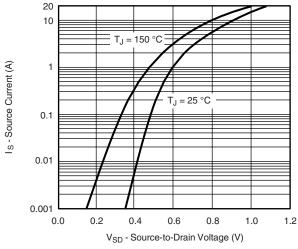


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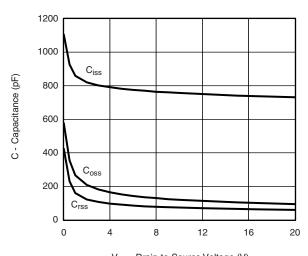


#### On-Resistance vs. Drain Current



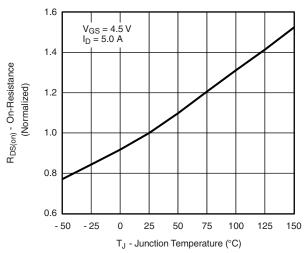


Source-Drain Diode Forward Voltage

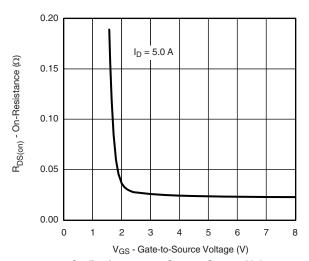


V<sub>DS</sub> - Drain-to-Source Voltage (V)





On-Resistance vs. Junction Temperature

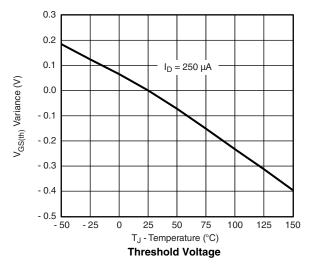


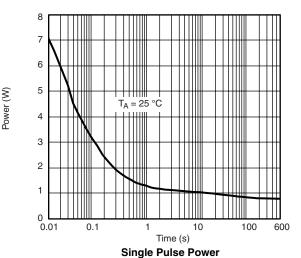
On-Resistance vs. Gate-to-Source Voltage

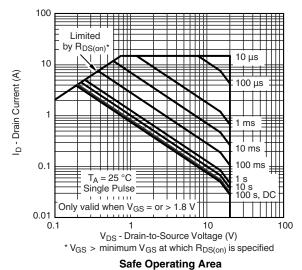
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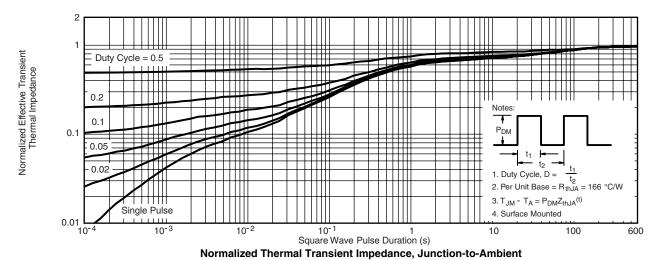
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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





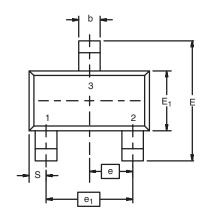


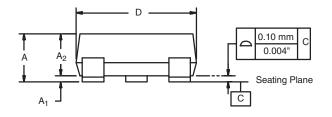


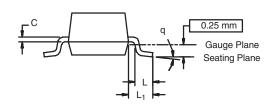
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## SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	METERS	INCHES			
	Min	Max	Min	Max		
Α	0.89	1.12	0.035	0.044		
A <sub>1</sub>	0.01	0.10	0.0004	0.004		
A <sub>2</sub>	0.88	1.02	0.0346	0.040		
b	0.35	0.50	0.014	0.020		
С	0.085	0.18	0.003	0.007		
D	2.80	3.04	0.110	0.120		
E	2.10	2.64	0.083	0.104		
E <sub>1</sub>	1.20	1.40	0.047	0.055		
е	0.95 BSC		0.0374 Ref			
e <sub>1</sub>	1.90 BSC		0.074	0.0748 Ref		
L	0.40	0.60	0.016	0.024		
L <sub>1</sub>	0.64 Ref		0.025	i Ref		
S	0.50 Ref		0.020	) Ref		
q	3°	8°	3°	8°		

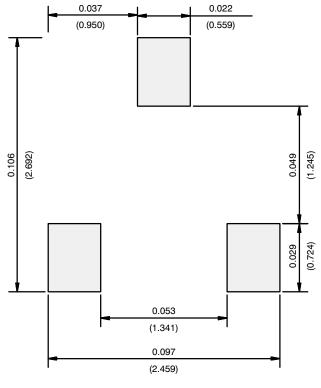
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## **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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